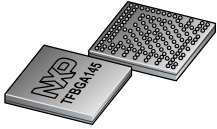


SOT2153-1

TFBGA145 very thin fine-pitch ball grid array, 145 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.07 mm body

14 December 2023

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	TFBGA145
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-04-2023
Manufacturer package code	98ASA01788D_O

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	-	1.07	-	mm
nominal pitch	-	0.5	-	mm



TFBGA145 very thin fine-pitch ball grid array, 145 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.07 mm body

2 Package outline

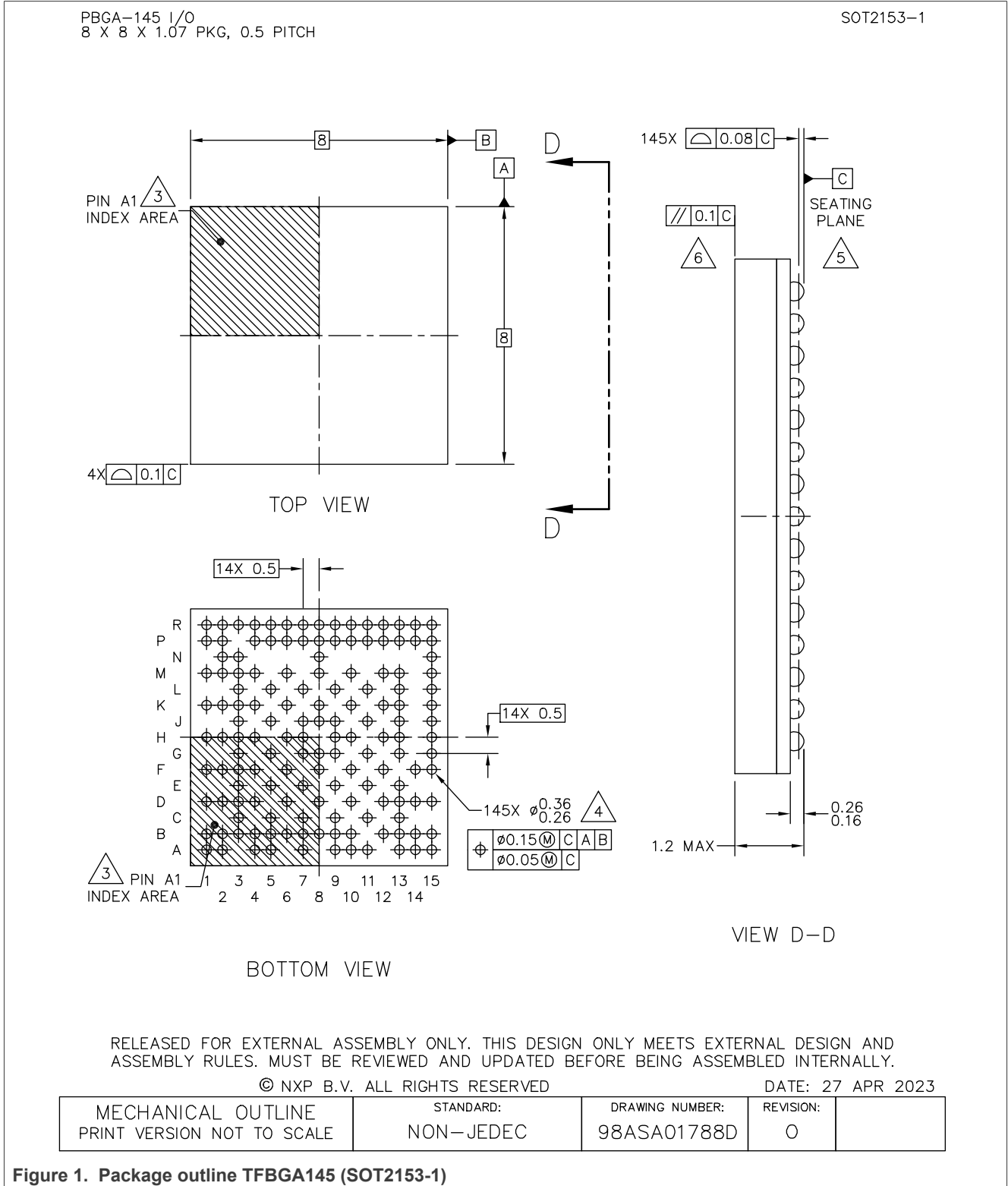
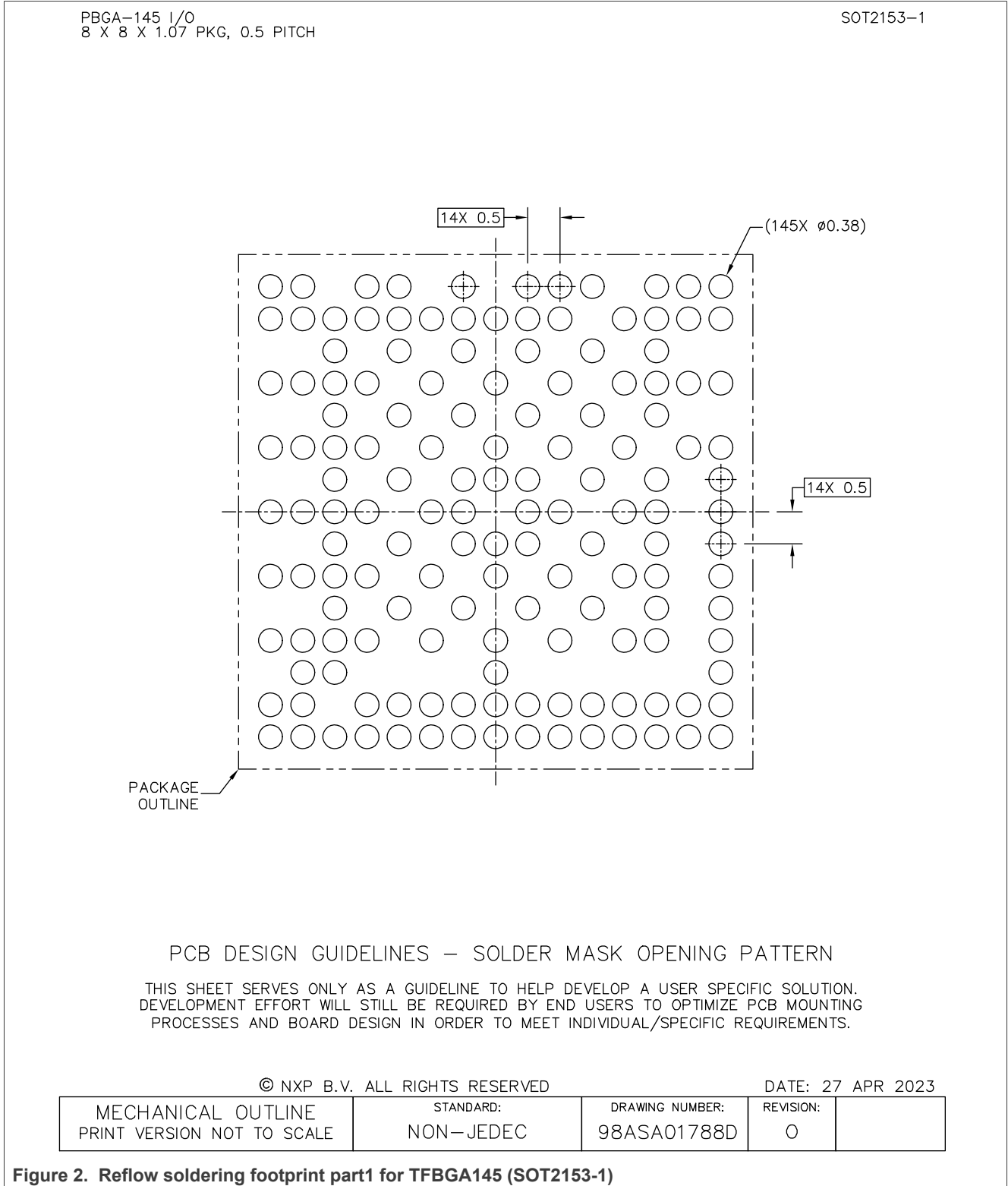


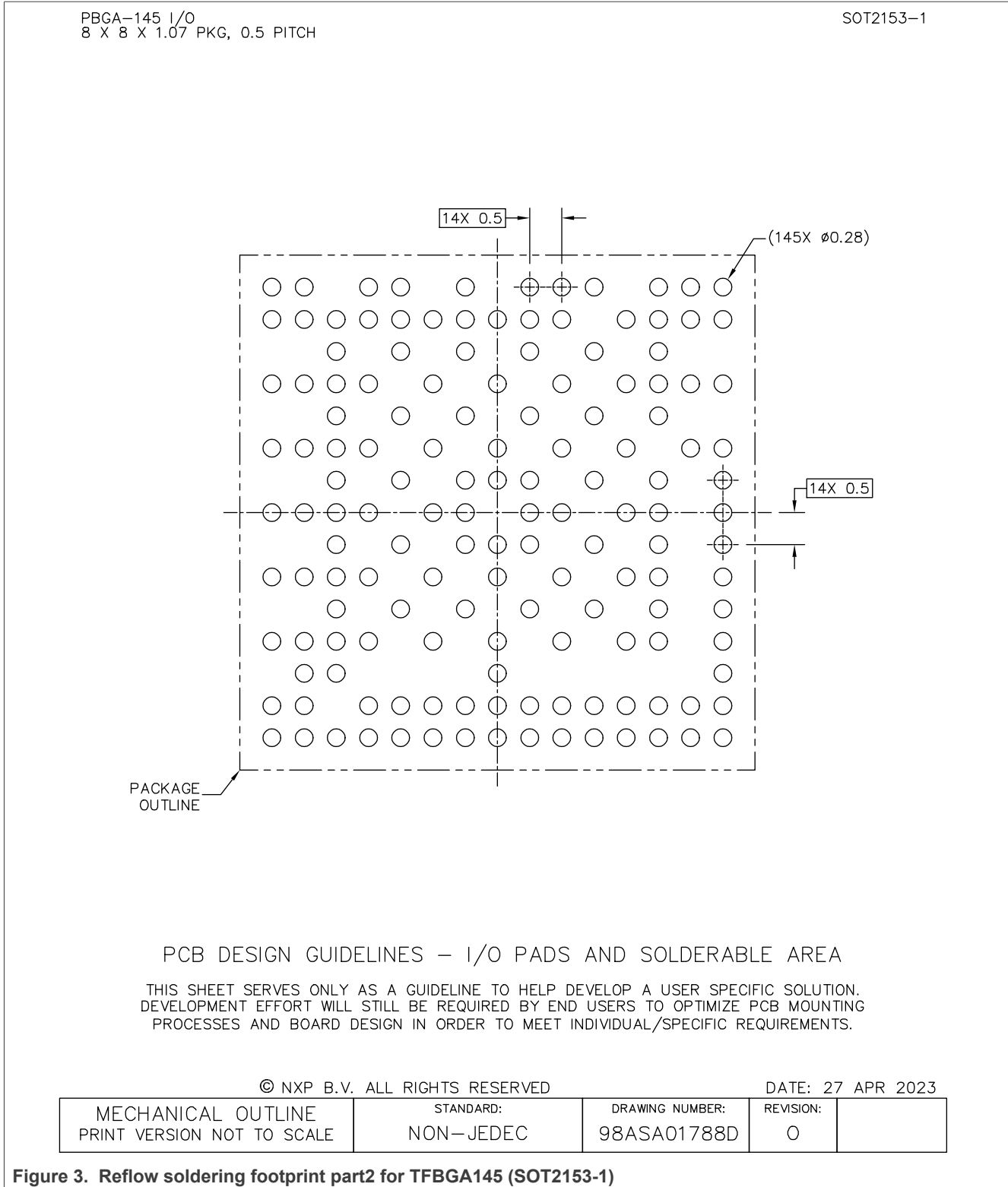
Figure 1. Package outline TFBGA145 (SOT2153-1)

TFBGA145 very thin fine-pitch ball grid array, 145 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.07 mm body

3 Soldering



TFBGA145 very thin fine-pitch ball grid array, 145 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.07 mm body



TFBGA145 very thin fine-pitch ball grid array, 145 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.07 mm body

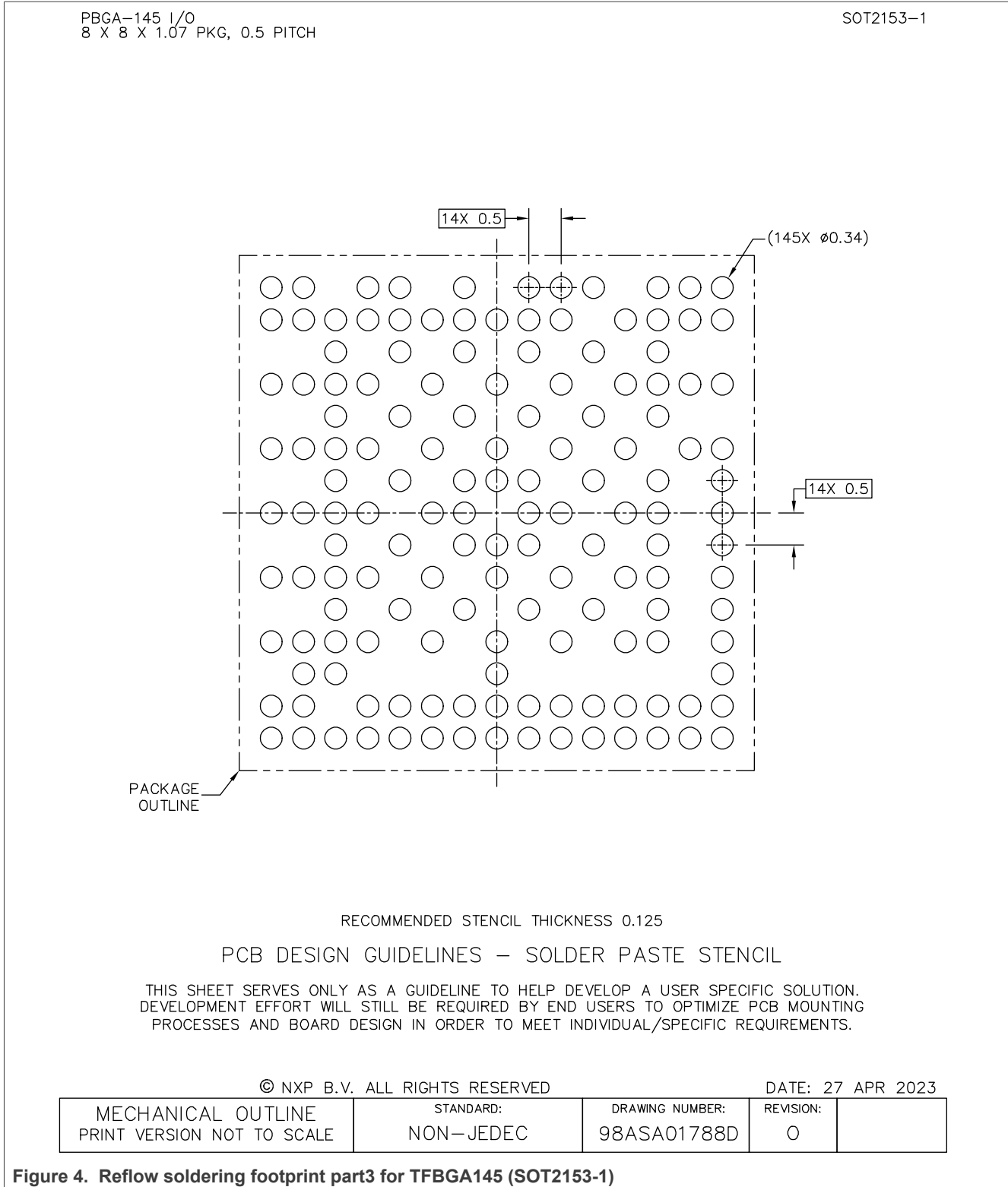


Figure 4. Reflow soldering footprint part3 for TFBGA145 (SOT2153-1)

TFBGA145 very thin fine-pitch ball grid array, 145 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.07 mm body

PBGA-145 I/O
8 X 8 X 1.07 PKG, 0.5 PITCH

SOT2153-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 27 APR 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01788D	REVISION: 0	
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Figure 5. Package outline note TFBGA145 (SOT2153-1)

4 Legal information

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TFBGA145 very thin fine-pitch ball grid array, 145 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.07 mm
body

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